The Stackup Legend below this is static.
If you change the stackup, update the Legend.

Layer Stack Up Detail for: Ref_Design.PcbDoc

Layer Name	Gerber Document	Copper Thickness	Dielectric Material
Top Solder Mask	(.GTS)		Solder Resist
Top Layer	(.GTL)	1.4mil	FR-4
Bottom Layer	(.GBL)	1.4mil	
Bottom Solder Mask	(.GBS)		Solder Resist

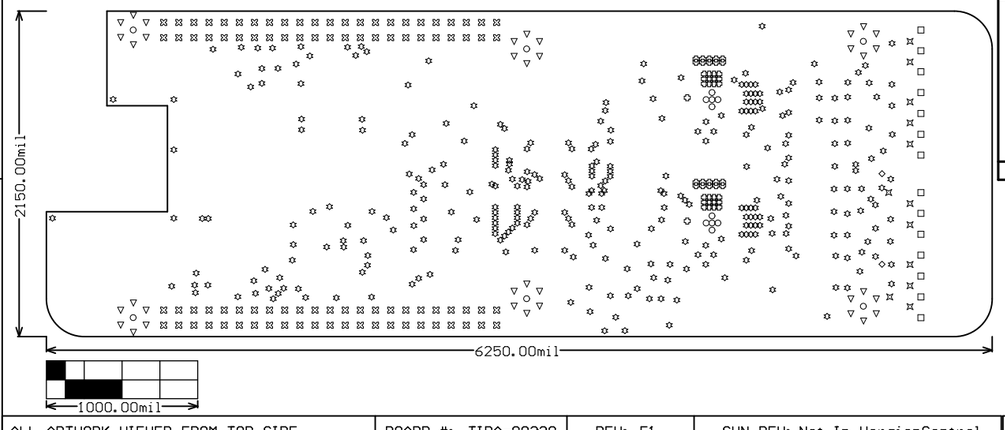
DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL
MIN. CLEARANCE: 0.2 mm
MIN. VIA PAD SIZE: 24 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
[ ] FR-408 [X] FR-4 High Tg [ ] OTHER _____
THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER _____
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/- _____
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/- _____

DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER _____

BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER _____
SOLDER RESIST COLOR:
[X] GREEN [ ] BLUE [ ] OTHER _____
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER _____
ARRAY/PANEL: [ ] CUT AND TRIM PER MECH LAYER 1
[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER
ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK



Symbol	Hit Count	Tool Size	Plated	Hole Type
○	10	7.874mil (0.2mm)	PTH	Round
✪	46	8mil (0.203mm)	PTH	Round
✡	328	12mil (0.305mm)	PTH	Round
▽	36	19.685mil (0.5mm)	PTH	Round
⌑	12	28mil (0.711mm)	PTH	Round
⊠	92	40.157mil (1.02mm)	PTH	Round
◇	2	43.307mil (1.1mm)	PTH	Round
□	14	47.244mil (1.2mm)	PTH	Round
○	6	137.795mil (3.5mm)	PTH	Round
	546 Total			

Drill Table

TEXAS INSTRUMENTS

PROJECT TITLE: BeagleBone Cape 8ch 0.5A Low Side for PLC
DESIGNED FOR: Public Release
FILE NAME: TIDA-00320_BeagleBone_Cape_8ch_LS.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00320	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = [illegible]ions			
PLOT NAME = Fabrication Drawing	GENERATED : 12/15/2014 5:06:46 PM	TEXAS INSTRUMENTS	

ENGINEER:	LAYOUT BY:
Ingolf Frank	Ingolf Frank
SCALE: 1.00	ALTIUM DESIGNER VERSION: 14.3.15.35511

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